



IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE

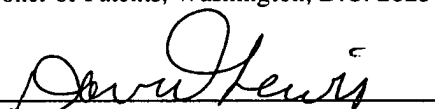
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APPLICANTS: Steven F. Reiber et al.
SERIAL NO.: 09/514,454
FILING DATE: February 25, 2000
TITLE: Dissipative Ceramic Bonding Tip
ATTY.DKT.NO.: PA1118US

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on the date printed below:

Date: December 6, 2000


David Lewis

COMMISSIONER FOR PATENTS
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Response to Restriction Requirement

Sir:

In response to the restriction requirement mailed November 8, 2000 (paper # 10)
please amend the claims as follows:

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DEC 18 2000
TC 1700 MAIL ROOM

In the claims

- 1 37. A method of using a bonding tip, comprising:
- 2 [providing] bonding a device using a bonding tip made with a dissipative material
- 3 that has a resistance low enough to prevent a discharge of charge to [a] said device [being
- 4 bonded] and high enough to avoid current flow large enough to damage said device
- 5 [being bonded;
- 6 heating the boding tip using electrical resistive heating; and
- 7 using the bonding tip to melt a bonding material].